



SYMBOL	S08			V08		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	.059	.064	.068	$\approx$	$\approx$	.047
A <sub>1</sub>	.004	.006	.0098	.002	.004	.006
A <sub>2</sub>	.055	.058	.061	.037	.039	.044
B	.013	.016	.020	.0138	$\approx$	.0192
C	.0075	.008	.0098	.0075	$\approx$	.0089
D	.189	.194	.196	.189	.194	.196
E	.150	.155	.157	.150	.155	.157
e	.050 BSC			.050 BSC		
H	.229	.236	.244	.230	.236	.244
h	.010	.013	.019	.010	.013	.019
L	.016	.025	.035	.016	.025	.035
$\alpha$	0°	5°	8°	0°	$\approx$	8°
REF	JEDEC MS-012			$\approx$		

**NOTES:**

- ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1982.
- DIMENSION 'D' DOES NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION SHALL NOT EXCEED .006" PER SIDE.
- DIMENSION 'E' DOES NOT INCLUDE MOLD PROTRUSION. ALLOWABLE MOLD PROTRUSION SHALL NOT EXCEED .010 INCH PER SIDE.
- LEAD FINISH: SOLDER PLATE

## 8 LEAD SOIC/TSOP (S08, V08)